

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Part Number : **CL10C331FB8NNNC**
- Description : **CAP, 330pF, 50V, ±1%, COG, 0603**

A. Samsung Part Number

CL 10 C 331 F B 8 N N N C
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor									
② Size	0603 (inch code)	L: 1.6 ± 0.1 mm	W: 0.8 ± 0.1 mm							
③ Dielectric	COG	⑧ Inner electrode		Ni						
④ Capacitance	330 pF	Termination		Cu						
⑤ Capacitance tolerance	±1 %	Plating		Sn 100% (Pb Free)						
⑥ Rated Voltage	50 V	⑨ Product		Normal						
⑦ Thickness	0.8 ± 0.1 mm	⑩ Special		Reserved for future use						
		⑪ Packaging		Cardboard Type, 7" reel						

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1MHz±10% 0.5~5Vrms
Q	1000 min	
Insulation Resistance	10,000Mohm or 500Mohm·μF Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	300% of the rated voltage
Temperature Characteristics	COG (From -55°C to 125°C, Capacitance change should be within ±30PPM/°C)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5% or ±0.5pF whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	1) Sn63Pb37 solder 235±5°C, 5±0.5sec. 2) SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5°C, 10±1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours \times 3 direction (x, y, z)
Humidity	Capacitance change : within $\pm 5\%$ or $\pm 0.5\text{pF}$ whichever is larger Q : 350 min IR : 1000Mohm or $50\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	40 \pm 2 $^{\circ}\text{C}$, 90~95%RH, 500+12/-0hrs
Moisture Resistance	Capacitance change : within $\pm 7.5\%$ or $\pm 0.75\text{pF}$ whichever is larger Q : 200 min IR : 500Mohm or $25\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With rated voltage 40 \pm 2 $^{\circ}\text{C}$, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within $\pm 3\%$ or $\pm 0.3\text{pF}$ whichever is larger Q : 350 min IR : 1000Mohm or $50\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature \rightarrow 25 $^{\circ}\text{C}$ \rightarrow Max. operating temperature \rightarrow 25 $^{\circ}\text{C}$ 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\text{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.